ASSOCIATION ELECTRONICS	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1					Form Type Distribute											
Supplier	Informa	tion														
Company	Company name*				Company unique ID			Unique ID Authority				Response Date*				
onsemi													2024-04-24			
Contact Name				Title - Contact				Phone - Contact*				Email - Contact*				
Product-E	Env-Stewar	ds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized	Authorized Representative*				Title - Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards				Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item			Number Mfr Item Name				Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type		
	ESD847			2MUT5G	MUT5G Low Cap TVS			2024-04-24				0.2847	mg	Each		
Manufacturing Process Information																
	Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MSI			L Rating	ing Peak Process Body Temperature Max Time at Pea			k Temperature Number of Reflow Cycles					
	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1			260 C 30		seconds 3							
Comments																
level 1 - maximum time at peak temperature during soldering is 10-30 seconds																
For more information regarding material composition please refer to page 3																

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.024	mg	Supplier	Silicon (Si)	7440-21-3		0.024	mg
Die Attach Epoxy	0.0378	mg		Epoxy resin	proprietary data		0.0038	mg
			Supplier	Cumene hydroperoxide	80-15-9		0.0002	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		0.0017	mg
			Supplier	Silver (Ag)	7440-22-4		0.0321	mg
Lead Frame	0.1083	mg	Supplier	Tin (Sn)	7440-31-5		0.0003	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0002	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.1075	mg
Mold Compound-Black	0.0828	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.0066	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0004	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0017	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.0716	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0025	mg
Plating	0.0269	mg	Supplier	Palladium (Pd)	7440-05-3		0.0025	mg
			В	Nickel (Ni)	7440-02-0		0.0243	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
Wire Bond - Au	0.0049	mg	Supplier	Gold (Au)	7440-57-5		0.0049	mg